

CMOS 8-bit Single Chip Microcomputer

Description

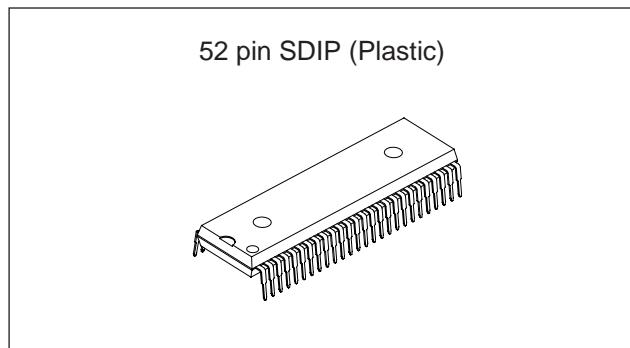
The CXP86213/86217, CXP86325/86333, CXP86441/86449/86461 are the CMOS 8-bit single chip microcomputer integrating on a single chip an A/D converter, serial interface, timer/counter, time-base timer, on-screen display function, I²C bus interface, PWM output, remote control reception circuit, HSYNC counter, watchdog timer, 32kHz timer/counter besides the basic configurations of 8-bit CPU, ROM, RAM, I/O ports.

The CXP86213/86217, CXP86325/86333, CXP86441/86449/86461 also provide a sleep function that enables to lower the power consumption.

Features

- A wide instruction set (213 instructions) which covers various types of data
 - 16-bit operation/multiplication and division/ Boolean bit operation instructions
- Minimum instruction cycle 250ns at 16MHz operation (4.5 to 5.5V)
122μs at 32kHz operation (2.7 to 5.5V)
- Incorporated ROM capacity 12K bytes (CXP86213) 24K bytes (CXP86325) 40K bytes(CXP86441)
16K bytes (CXP86217) 32K bytes (CXP86333) 48K bytes (CXP86449)
60K bytes (CXP86461)
- Incorporated RAM capacity 352 bytes (CXP86213/86217) 704 bytes (CXP86325/86333)
1536 bytes (CXP86441/86449/86461)
(Excludes VRAM for on-screen display and sprite RAM)
- Peripheral functions
 - A/D converter 8 bits, 6 channels, successive approximation method
(Conversion time of 3.25μs at 16MHz)
 - Serial interface 8-bit clock sync type, 1 channel
 - Timer 8-bit timer
 - On-screen display (OSD) function 8-bit timer/counter
19-bit time-base timer
32kHz timer/counter
12 × 16 dots, 128 character types (CXP86213/86217),
256 character types (CXP86325/86333),
384 character types (CXP86441/86449/86461)
15 character colors, 2 lines × 24 characters,
frame background 8 colors/ half blanking,
background on full screen 15 colors/ half blanking
edging/ shadowing/ rounding for every line,
background with shadow for every character (CXP86441/86449/86461),
double scanning,
sprite OSD (CXP86441/86449/86461),
12 × 16 dots, 1 screen, 8 colors for every dot
 - I²C bus interface 8 bits, 6 channels
 - PWM output 14 bits, 1 channel
 - Remote control reception circuit 8-bit pulse measurement counter, 6-stage FIFO
 - HSYNC counter 2 channels
 - Watchdog timer
- Interruption 13 factors, 13 vectors, multi-interruption possible
- Standby mode Sleep
- Package 52-pin plastic SDIP
- Piggyback/evaluator CXP86490 64-pin ceramic PSDIP (Supports custom font)

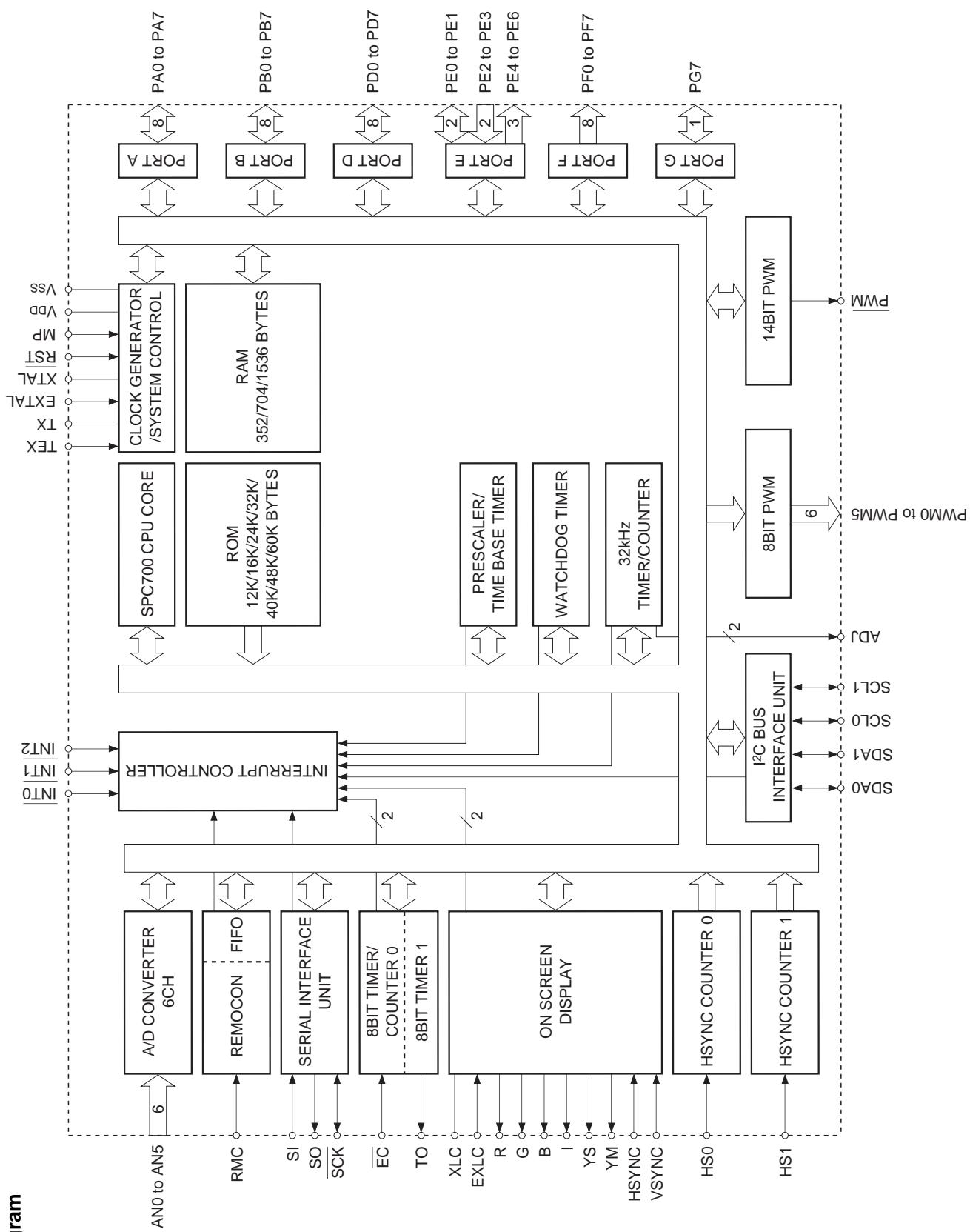
Purchase of Sony's I²C components conveys a licence under the Philips I²C Patent Rights to use these components in an I²C system, provided that the system conforms to the I²C Standard Specifications as defined by Philips.

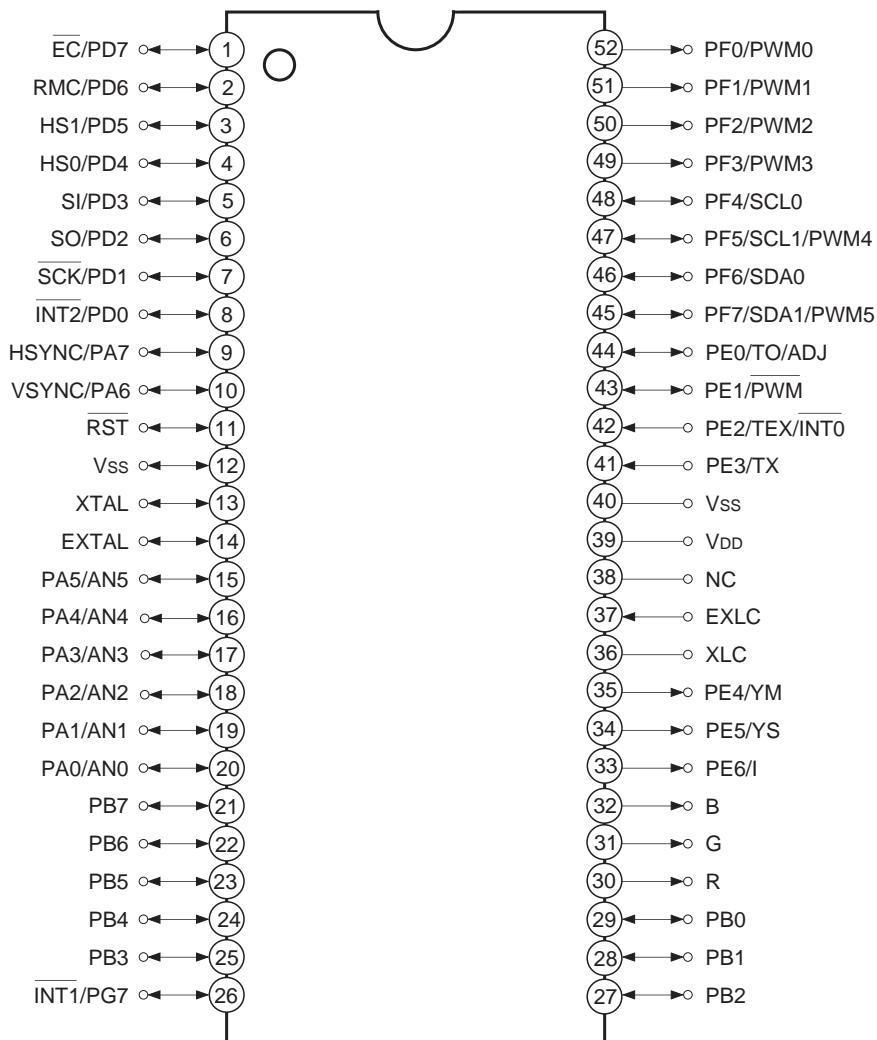


Structure

Silicon gate CMOS IC

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Pin Assignment (Top View)**Note)**

1. NC (Pin 38) is left open.
2. Vss (Pins 12 and 40) are both connected to GND.

Pin Description

Symbol	I/O	Description	
PA0/AN0 to PA5/AN5	I/O/ Analog input	(Port A) 8-bit I/O port. I/O can be set in a unit of single bits. (8 pins)	Analog inputs to A/D converter. (6 pins)
PA6/VSYNC	I/O/Input		OSD display vertical sync signal input.
PA7/HSYNC	I/O/Input		OSD display horizontal sync signal input.
PB0 to PB7	I/O	(Port B) 8-bit I/O port. I/O can be set in a unit of single bits. (8 pins)	
PD0/INT2	I/O/Input	(Port D) 8-bit I/O port. I/O can be set in a unit of single bits. Can drive 12mA synk current. (8 pins)	External interruption request input. Active at the falling edge.
PD1/SCK	I/O/I/O		Serial clock I/O.
PD2/SO	I/O/Output		Serial data output.
PD3/SI	I/O/Input		Serial data input.
PD4/HS0	I/O/Input		HSYNC counter (CH0) input.
PD5/HS1	I/O/Input		HSYNC counter (CH1) input.
PD6/RMC	I/O/Input		Remote control reception circuit input.
PD7/EC	I/O/Input		External event input for timer/counter.
PE0/TO/ADJ	I/O/Output/ Output	(Port E) Bits 0 and 1 are I/O port; I/O can be set in a unit of single. Bits 2 and 3 are input port. Bits 4, 5 and 6 are output port. (7 pins)	Rectangular wave output for 8-bit timer/counter. 32kHz oscillation frequency dividing output.
PE1/PWM	I/O/Output		14-bit PWM output.
PE2/TEX/INT0	Input/Input/ Input		Connects a crystal for 32kHz timer/counter clock oscillation. When used as an event counter, input to TEX pin and leave TX pin open.
PE3/TX	Input/Output		
PE4/YM	Output/Output		
PE5/YS	Output/Output		
PE6/I	Output/Output		
B	Output		OSD display 6-bit output. (6 pins)
G	Output		
R	Output		

Symbol	I/O	Description	
PF0/PWM0 to PF3/PWM3	Output/Output	(Port F) 8-bit output port. Open drain output of large current (12mA) and N channel.	8-bit PWM output. (4 pins)
PF4/SCL0	Output/I/O		I ² C bus interface transfer clock I/O. (2 pins)
PF5/SCL1/ PWM4	Output/I/O/ Output	Lower 4 bits are medium drive voltage (12V); upper 4 bits are 5V drive. (8 pins)	8-bit PWM output.
PF6/SDA0	Output/I/O		I ² C bus interface transfer data I/O. (2 pins)
PF7/SDA1/ PWM5	Output/I/O/ Output		8-bit PWM output.
PG7/INT1	I/O/Input	(Port G) 1-bit I/O port.	External interruption request input. Active at the falling edge.
EXTAL	Input	Connects a crystal for system clock oscillation. When a clock is supplied externally, input to EXTAL pin and input a reversed phase clock to XTAL pin.	
XTAL	Output		
RST	Input	System reset; active at Low level.	
EXLC	Input	OSD display clock oscillation I/O. Oscillation frequency is determined by the external L and C.	
XLC	Output		
NC		No connected.	
V _{DD}		Positive power supply.	
V _{ss}		GND. Connect two V _{ss} pins to GND.	

Input/Output Circuit Formats for Pins

Pin	Circuit format	When reset
PA0/AN0 to PA5/AN5 6 pins	<p>Port A</p>	Hi-Z
PA6/VSYNC PA7/HSYNC 2 pins	<p>Port A</p>	Hi-Z
PB0 to PB7 PG7/INT1 9 pins	<p>Port B</p> <p>Port G</p>	Hi-Z
PF0/PWM0 to PF3/PWM3 4 pins	<p>Port F</p>	Hi-Z

Pin	Circuit format	When reset
PD0/INT2 PD3/SI PD4/HS0 PD5/HS1 PD6/RMC PD7/EC	<p>Port D</p> <p>INT2, SI, HS0, HS1, RMC, EC</p>	Hi-Z
PD1/SCK PD2/SO	<p>Port D</p> <p>SCK, SO</p> <p>SIO output enable</p> <p>Port D data</p> <p>Port D direction "0" when reset</p> <p>Data bus</p> <p>RD (Port D)</p> <p>SCK only</p>	Hi-Z
PE0/TO/ADJ	<p>Port E</p> <p>Internal reset signal</p> <p>Port E data "1" when reset</p> <p>MPX</p> <p>ADJ16K*¹ ADJ2K*¹</p> <p>Port E function selection (Upper) Port E function selection (Lower)</p> <p>Port E direction "00" when reset "1" when reset</p> <p>Data bus</p> <p>RD (Port E)</p> <p>*¹ ADJ signals are frequency dividing outputs for 32kHz oscillation frequency adjustment. ADJ2K provides usage as buzzer output.</p> <p>*² Pull-up resistors approx. 150kΩ</p>	High level (with the resistor of pull-up transistor ON when reset)

Pin	Circuit format	When reset
PE1/PWM 1 pin		High level
PE2/TEX/INT0 PE3/TX 2 pins		Oscillation halted Port input
PE4/YM PE5/YS PE6/I 3 pins	<p>Writing data to output polarity register and port data register brings output to active.</p>	Hi-Z

Pin	Circuit format	When reset
PF4/SCL0 PF5/SCL1/PWM4 PF6/SDA0 PF7/SDA1/PWM5	<p>Port F</p> <p>SCL, SDA</p> <p>I²C bus enable</p> <p>PWM4, PWM5</p> <p>Port F function selection "0" when reset</p> <p>Port F data "1" when reset</p> <p>Schmitt input</p> <p>SCL, SDA (I²C bus circuit)</p> <p>* Large current 12mA</p> <p>To internal I²C pins (SCL1 for SCL0)</p> <p>BUS SW</p>	Hi-Z
R G B	<p>R, G, B</p> <p>Output polarity "0" when reset</p> <p>Writing data to output polarity register brings output to active.</p>	Hi-Z
EXLC XLC	<p>Oscillation control</p> <p>EXLC</p> <p>XLC</p> <p>IP</p> <p>OSD display clock</p>	Oscillation halted
EXTAL XTAL	<p>EXTAL</p> <p>XTAL</p> <p>IP</p> <ul style="list-style-type: none"> Diagram shows the circuit composition during oscillation. Feedback resistor is removed during stop mode. (This device does not enter the stop mode.) 	Oscillation
RST	<p>Pull-up resistor</p> <p>Mask option (OP)</p> <p>Schmitt input</p>	Low level
1 pin		

Absolute Maximum Ratings(V_{ss} = 0V reference)

Item	Symbol	Ratings	Unit	Remarks
Supply voltage	V _{DD}	−0.3 to +7.0	V	
Input voltage	V _{IN}	−0.3 to +7.0* ¹	V	
Output voltage	V _{OUT}	−0.3 to +7.0* ¹	V	
Medium drive output voltage	V _{OUTP}	−0.3 to +15.0	V	
High level output current	I _{OH}	−5	mA	
High level total output current	ΣI _{OH}	−50	mA	Total of all output pins
Low level output current	I _{OL}	15	mA	Ports excluding large current output (value per pin)
	I _{OLC}	20	mA	Large current output ports (value per pin* ²)
Low level total output current	ΣI _{OL}	130	mA	Total of all output pins
Operating temperature	T _{opr}	−20 to +75	°C	
Storage temperature	T _{stg}	−55 to +150	°C	
Allowable power dissipation	P _D	375	mW	52-pin SDIP

*¹ V_{IN} and V_{OUT} should not exceed V_{DD} + 0.3V.*² The large current output port is Port D (PD) and Port F (PF).

Note) Usage exceeding absolute maximum ratings may permanently impair the LSI. Normal operation should be conducted under the recommended operating conditions. Exceeding those conditions may adversely affect the reliability of the LSI.

Recommended Operating Conditions(V_{ss} = 0V reference)

Item	Symbol	Min.	Max.	Unit	Remarks
Supply voltage	V _{DD}	4.5	5.5	V	Guaranteed operation range for 1/2 and 1/4 frequency dividing modes
		3.5	5.5	V	Guaranteed operation range for 1/16 frequency dividing mode or sleep mode
		2.7	5.5	V	Guaranteed operation range for TEX mode
		—	—	V	Guaranteed data hold range for stop mode* ⁵
High level input voltage	V _{IH}	0.7V _{DD}	V _{DD}	V	* ¹
	V _{IHS}	0.8V _{DD}	V _{DD}	V	* ²
	V _{IHEX}	V _{DD} − 0.4	V _{DD} + 0.3	V	EXTAL pin* ³ , TEX pin* ⁴
Low level input voltage	V _{IL}	0	0.3V _{DD}	V	* ¹
	V _{ILS}	0	0.2V _{DD}	V	* ²
	V _{ILEX}	−0.3	0.4	V	EXTAL pin* ³ , TEX pin* ⁴
Operating temperature	T _{opr}	−20	+75	°C	

*¹ PA1 to 5, PB3 to 7, PD2, PE0, PE1, PE3, SCL0 to 1, SDA0 to 1 pins*² VSYNC, HSYNC, INT2, SCK, SI, HS0, HS1, RMC, EC, INT0, INT1, RST, PB0, PB1, PB2 pins*³ Specifies only during external clock input.*⁴ Specifies only during external event count input.*⁵ This device does not enter the stop mode.

Electrical Characteristics**DC characteristics**

(Ta = -20 to +75°C, Vss = 0V reference)

Item	Symbol	Pins	Conditions	Min.	Typ.	Max.	Unit
High level output voltage	V _{OH}	PA, PB, PD, PE0 to PE1, PE4 to PE6, PG7, R, G, B	V _{DD} = 4.5V, I _{OH} = -0.5mA	4.0			V
			V _{DD} = 4.5V, I _{OH} = -1.2mA	3.5			V
Low level output voltage	V _{OL}	PA, PB, PD, PE0 to PE1, PE4 to PE6, PF0 to PF3, PG7, R, G, B	V _{DD} = 4.5V, I _{OL} = 1.8mA			0.4	V
			V _{DD} = 4.5V, I _{OL} = 3.6mA			0.6	V
		PD, PF PF4 to PF7 (SCL0, SCL1, SDA0, SDA1)	V _{DD} = 4.5V, I _{OL} = 12.0mA			1.5	V
			V _{DD} = 4.5V, I _{OL} = 3.0mA			0.4	V
			V _{DD} = 4.5V, I _{OL} = 4.0mA			0.6	V
Input current	I _{IHE}	EXTAL	V _{DD} = 5.5V, V _{IH} = 5.5V	0.5		40	μA
	I _{IIE}		V _{DD} = 5.5V, V _{IL} = 0.4V	-0.5		-40	μA
	I _{IHT}	TEX	V _{DD} = 5.5V, V _{IH} = 5.5V	0.1		10	μA
	I _{ILT}		V _{DD} = 5.5V, V _{IL} = 0.4V	-0.1		-10	μA
	I _{ILR}	RST*1		-1.5		-400	μA
I/O leakage current	I _{Iz}	PA, PB, PD, PE, R, G, B, RST*1	V _{DD} = 5.5V, V _I = 0, 5.5V			±10	μA
Open drain I/O leakage current (in N-ch Tr off state)	I _{LOH}	PF0 to PF3	V _{DD} = 5.5V, V _{OH} = 12.0V			50	μA
		PF4 to PF7	V _{DD} = 5.5V, V _{OH} = 5.5V			10	μA
I ² C bus switch connection impedance (in output Tr off state)	R _{BS}	SCL0: SCL1 SDA0: SDA1	V _{DD} = 4.5V V _{SCL0} = V _{SCL1} = 2.25V V _{SDA0} = V _{SDA1} = 2.25V			120	Ω
Supply current*2	I _{DD1}	V _{DD}	1/2 frequency dividing mode V _{DD} = 5.5V, 16MHz crystal oscillation (C ₁ = C ₂ = 15pF)		18	28	mA
	I _{DD2}		V _{DD} = 3.3V, 32MHz crystal oscillation (C ₁ = C ₂ = 47pF)		30	80	μA
	I _{DDS1}		SLEEP mode V _{DD} = 5.5V, 16MHz crystal oscillation (C ₁ = C ₂ = 15pF)		1.2	2.1	mA
	I _{DDS2}		V _{DD} = 3.3V, 32MHz crystal oscillation (C ₁ = C ₂ = 47pF)		12	35	μA
	I _{DDS3}		STOP mode*3 V _{DD} = 5.5V, termination of 16MHz and 32MHz oscillation	—	—	—	μA

Item	Symbol	Pins	Conditions	Min.	Typ.	Max.	Unit
Input capacitance	C_{IN}	PA, PB, PD, PE0 to PE3, R, G, B, PF4 to PF7, EXTAL, TEX, EXLC, \overline{RST}	Clock 1MHz 0V other than the measured pins		10	20	pF

*¹ For \overline{RST} pin, specifies the input current when pull-up resistance is selected, and specifies the leakage current when non-resistor is selected.

*² When all output pins are left open. Specifies only when the OSD oscillation is halted.

*³ This device does not enter the stop mode.

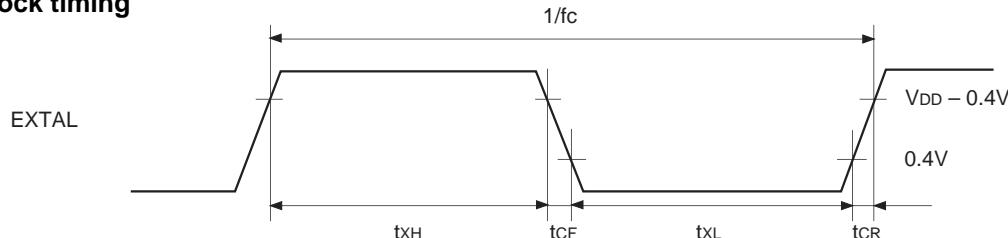
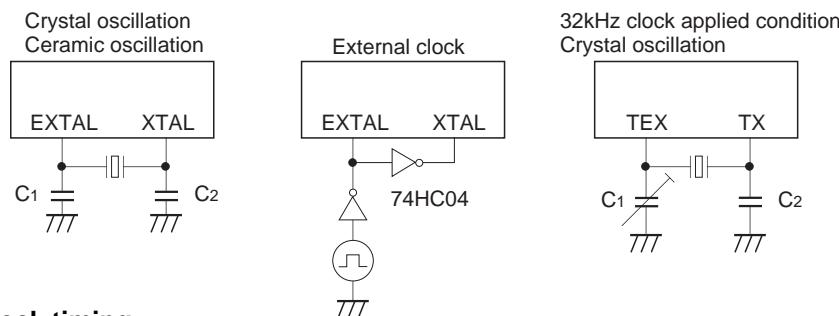
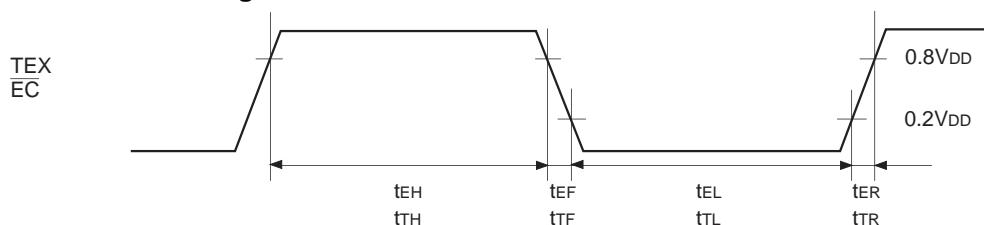
AC Characteristics**(1) Clock timing**

(Ta = -20 to +75°C, VDD = 4.5 to 5.5V, Vss = 0V reference)

Item	Symbol	Pins	Conditions	Min.	Typ.	Max	Unit
System clock frequency	fc	XTAL EXTAL	Fig. 1, Fig. 2	8		16	MHz
System clock input pulse width	t _{XL} , t _{XH}	EXTAL	Fig. 1, Fig. 2 External clock drive	28			ns
System clock input rise and fall times	t _{CR} , t _{CF}	EXTAL	Fig. 1, Fig. 2 External clock drive			200	ns
Event count input clock pulse width	t _{EH} , t _{EL}	EC	Fig. 3	4t _{sys} *1			ns
Event count input clock rise and fall times	t _{ER} , t _{EF}	EC	Fig. 3			20	ms
System clock frequency	fc	TEX TX	V _{DD} = 2.7 to 5.5V Fig. 2 (32kHz clock applied conditions)		32.768		kHz
Event count input clock pulse width	t _{TL} , t _{TH}	TEX	Fig. 3	10			μs
Event count input clock rise and fall times	t _{TR} , t _{TF}	TEX	Fig. 3			20	ms

*1 t_{sys} indicates three values according to the contents of the clock control register (CLC: 00FEh) upper 2 bits (CPU clock selection).

t_{sys} (ns) = 2000/fc (Upper 2 bits = "00"), 4000/fc (Upper 2 bits = "01"), 16000/fc (Upper 2 bits = "11")

Fig. 1. Clock timing**Fig. 2. Clock applied conditions****Fig. 3. Event count clock timing**

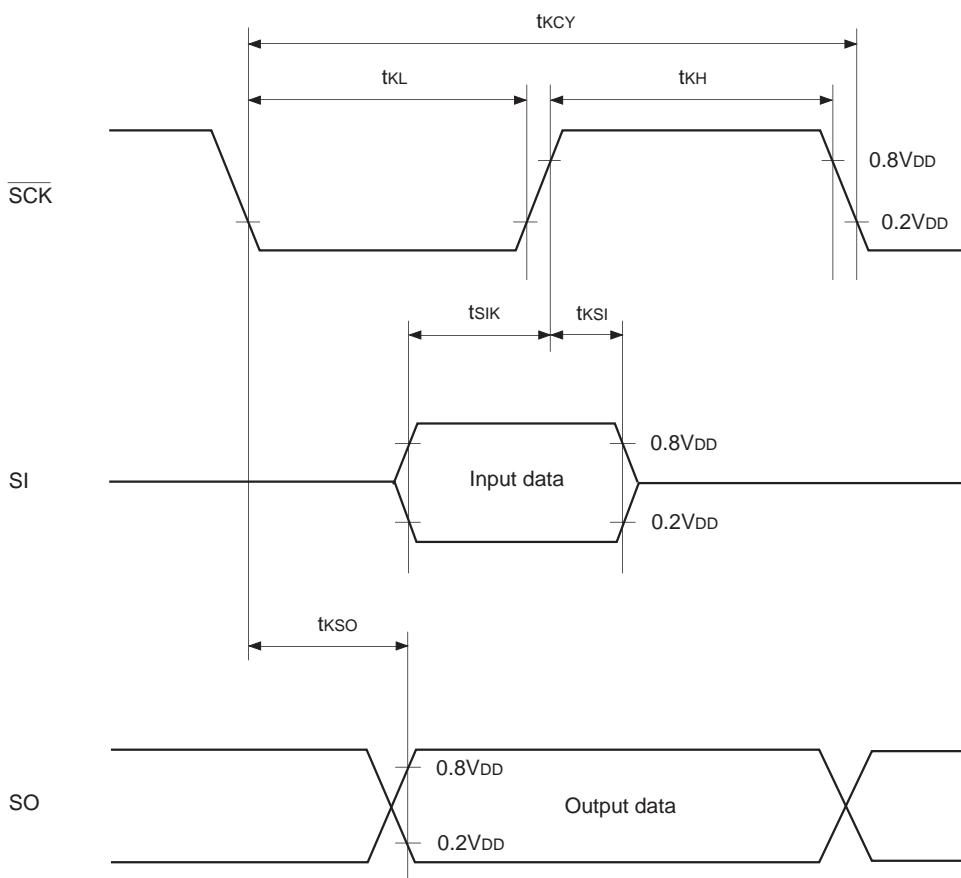
(2) Serial transfer

(Ta = -20 to +75°C, VDD = 4.5 to 5.5V, Vss = 0V reference)

Item	Symbol	Pins	Conditions	Min.	Max.	Unit
<u>SCK</u> cycle time	t _{KCY}	<u>SCK</u>	Input mode	1000		ns
			Output mode	8000/fc		ns
<u>SCK</u> High and Low level width	t _{KL} t _{KH}	<u>SCK</u>	SCK input mode	400		ns
			SCK output mode	4000/fc – 50		ns
SI input setup time (for SCK ↑)	t _{SIK}	SI	SCK input mode	100		ns
			SCK output mode	200		ns
SI hold time (for SCK ↑)	t _{ksi}	SI	SCK input mode	200		ns
			SCK output mode	100		ns
<u>SCK</u> ↓ → SO delay time	t _{KSO}	SO	SCK input mode		200	ns
			SCK output mode		100	ns

Note) The load of SCK output mode and SO output delay time is 50pF + 1TTL.

Fig. 4. Serial transfer timing

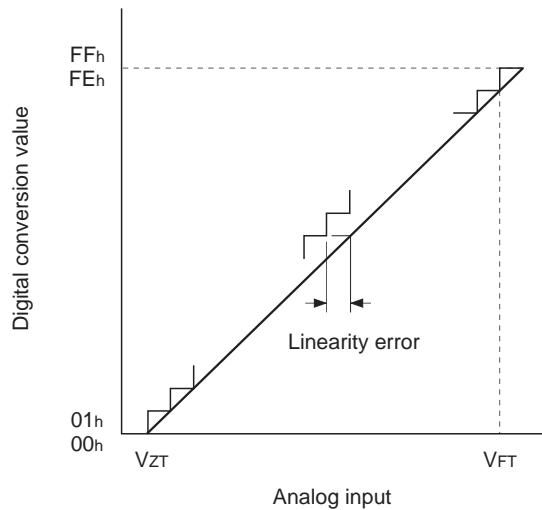


(3) A/D converter

(Ta = -20 to +75°C, V_{DD} = 4.5 to 5.5V, V_{ss} = 0V reference)

Item	Symbol	Pins	Conditions	Min.	Typ.	Max.	Unit
Resolution						8	Bits
Linearity error						±3	LSB
Zero transition voltage	V _{ZT} *1		T _a = 25°C V _{DD} = 5.0V V _{ss} = 0V	-10	10	70	mV
Full-scale transition voltage	V _{FT} *2			4910	4970	5030	mV
Conversion time	t _{CONV}			26/f _{ADC} *3			μs
Sampling time	t _{SAMP}			6/f _{ADC} *3			μs
Analog input voltage	V _{IAN}	AN0 to AN5		0		V _{DD}	V

Fig. 5. Definitions of A/D converter terms



*1 V_{ZT}: Value at which the digital conversion value changes from 00h to 01h and vice versa.

*2 V_{FT}: Value at which the digital conversion value changes from FEh to FFh and vice versa.

*3 f_{ADC} indicates the below values due to the contents of bit 6 (CKS) of the A/D control register (ADC: 00F6h):

$$f_{ADC} = f_c \text{ (CKS = "0"), } f_c/2 \text{ (CKS = "1")}$$

(4) Interruption, reset input (Ta = -20 to +75°C, V_{DD} = 4.5 to 5.5V, V_{ss} = 0V reference)

Item	Symbol	Pins	Conditions	Min.	Max.	Unit
External interruption High, Low level width	t _{IH} t _{IL}	<u>INT0</u> <u>INT1</u> <u>INT2</u>		1		μs
Reset input Low level width	t _{RSL}	<u>RST</u>		32/fc		μs

Fig. 6. Interruption input timing

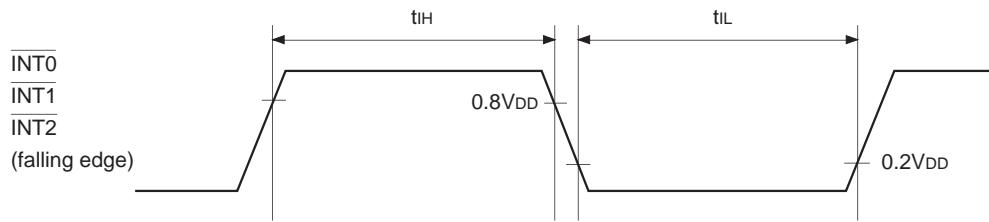
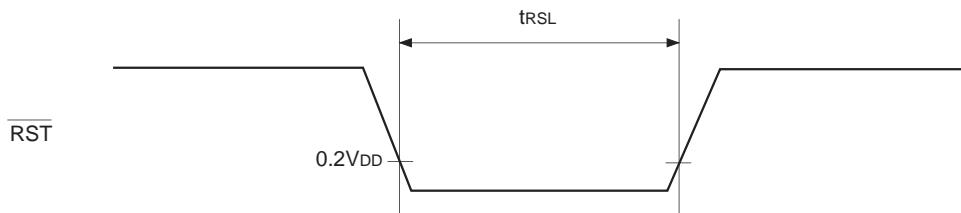


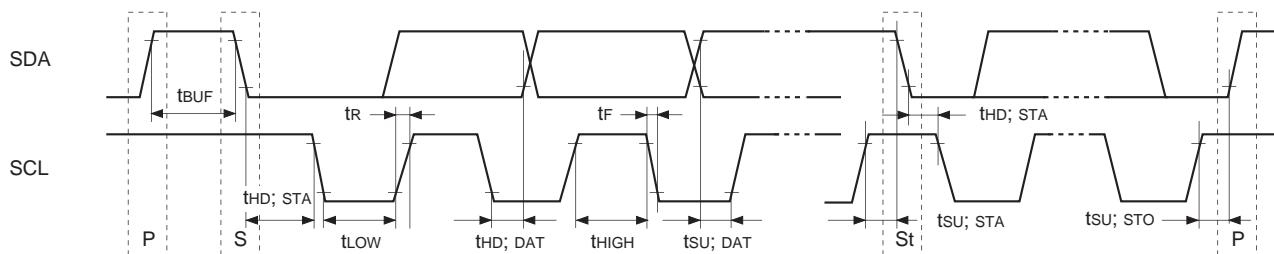
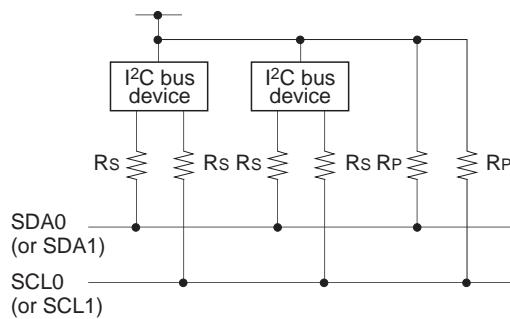
Fig. 7. RST input timing



(5) I²C bus timing(Ta = -20 to +75°C, V_{DD} = 4.5 to 5.5V, V_{SS} = 0V reference)

Item	Symbol	Pins	Conditions	Min.	Max.	Unit
SCL clock frequency	f _{SCL}	SCL		0	100	kHz
Bus-free time before starting transfer	t _{BUF}	SDA, SCL		4.7		μs
Hold time for starting transfer	t _{HD; STA}	SDA, SCL		4.0		μs
Clock Low level width	t _{LOW}	SCL		4.7		μs
Clock High level width	t _{HIGH}	SCL		4.0		μs
Setup time for repeated transfers	t _{SU; STA}	SDA, SCL		4.7		μs
Data hold time	t _{HD; DAT}	SDA, SCL		0*1		μs
Data setup time	t _{SU; DAT}	SDA, SCL		250		ns
SDA, SCL rise time	t _R	SDA, SCL			1	μs
SDA, SCL fall time	t _F	SDA, SCL			300	ns
Setup time for transfer completion	t _{SU; STO}	SDA, SCL		4.7		μs

*1 The data hold time should be 300ns or more because the SCL rise time (300ns Max.) is not included in it.

Fig. 8. I²C bus transfer timingFig. 9. I²C bus device recommended circuit

- A pull-up resistor (Rp) must be connected to SDA0 (or SDA1) and SCL0 (or SCL1).
- The SDA0 (or SDA1) and SCL0 (or SCL1) series resistance (Rs) can be used to reduce the spike noise caused by CRT flashover.

(6) OSD timing

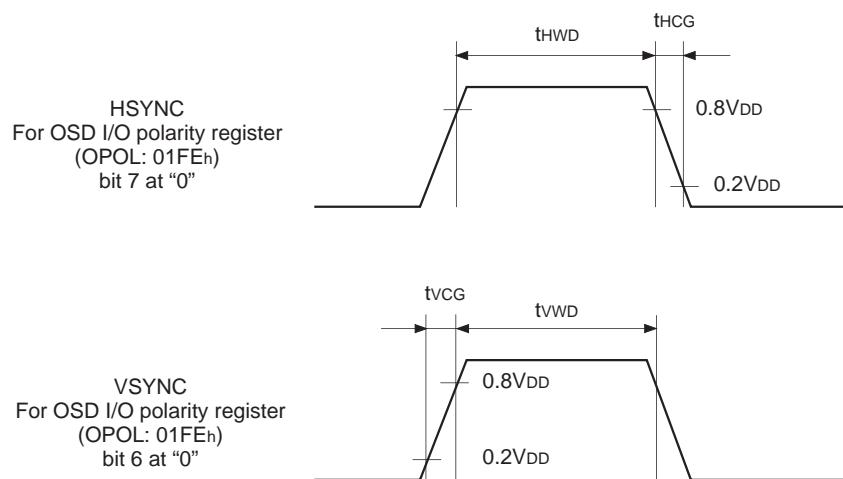
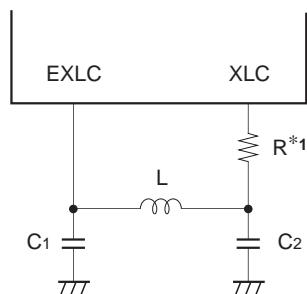
(Ta = -20 to +75°C, V_{DD} = 4.5 to 5.5V, V_{SS} = 0V reference)

Item	Symbol	Pins	Conditions	Min.	Max	Unit
OSD clock frequency	fosc	EXLC XLC	Fig. 11	4	28*1	MHz
H SYNC pulse width	t _{HWD}	H SYNC	Fig. 10	2		μs
V SYNC pulse width	t _{VWD}	V SYNC	Fig. 10	1		H*2
H SYNC afterwrite rise and fall times	t _{HCG}	H SYNC	Fig. 10		200	ns
V SYNC beforewrite rise and fall times	t _{VCG}	V SYNC	Fig. 10		1.0	μs

*1 The maximum value of fosc is specified with the following equation.

$$\text{fosc [max]} \leq \text{fc} \times 1.9$$

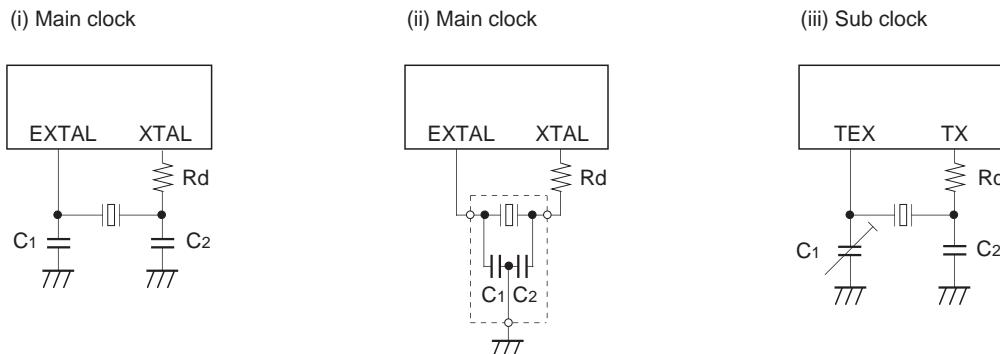
*2 H indicates 1H SYNC period.

Fig. 10. OSD timing**Fig. 11. LC oscillation circuit connection**

*1 The series resistor for XLC is used to reduce the frequency of occurrence of the undesired radiation.

Appendix

Fig. 12. Recommended oscillation circuit



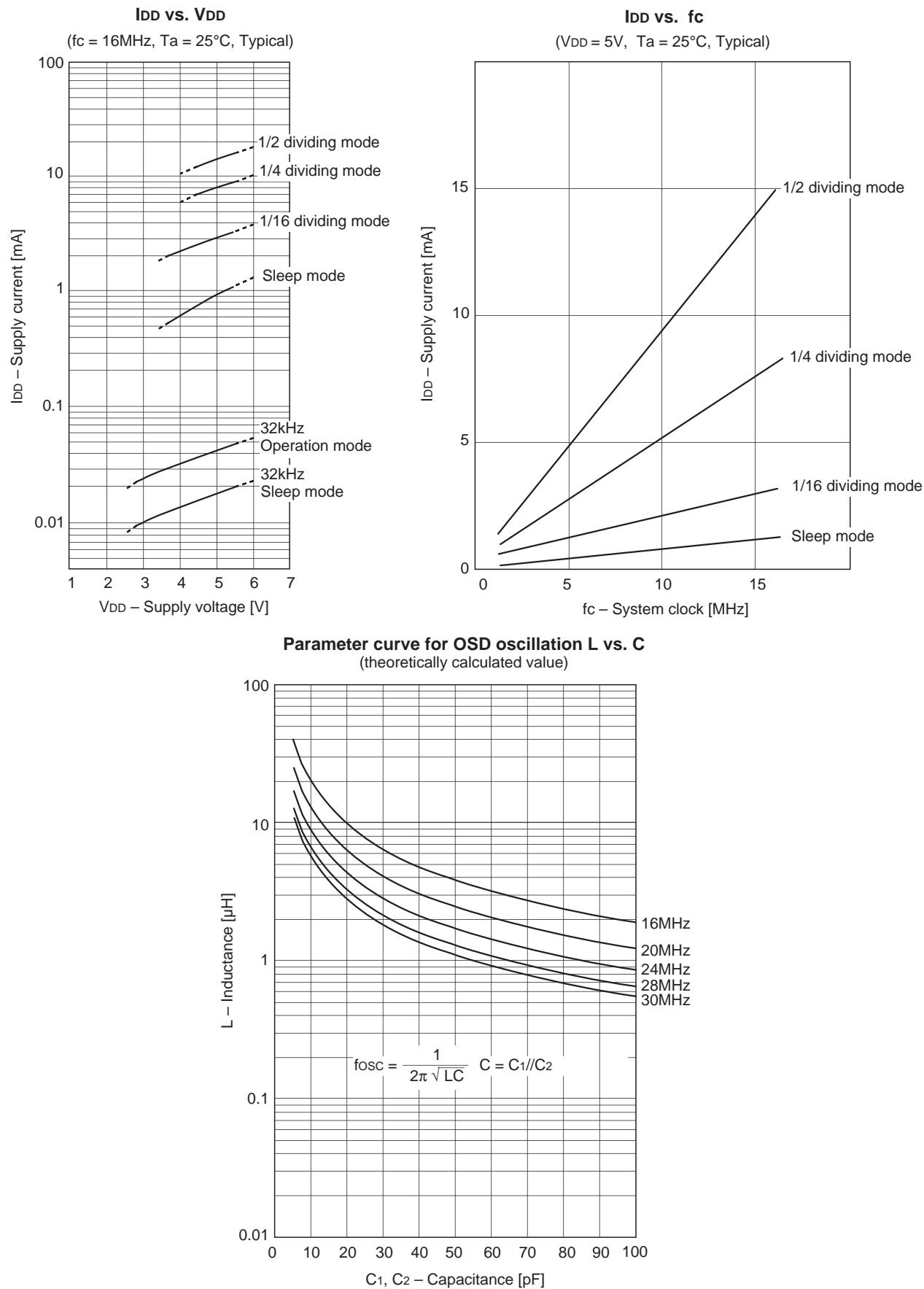
Manufacture	Model	fc (MHz)	C ₁ (pF)	C ₂ (pF)	Rd (Ω)	Circuit example		
MURATA MFG CO., LTD	CSA10.0MTZ	10.0	30	30	0* ¹	(i)		
	CSA12.0MTZ	12.0						
	CSA16.00MXZ040	16.0	5	5		(ii)		
	CST10.0MTW*	10.0	30	30				
	CST12.0MTW*	12.0						
	CST16.00MXW0C1*	16.0	5	5				
RIVER ELETEC CO., LTD.	HC-49/U03	8.0	18	18	330* ¹	(i)		
		12.0	12	12				
		16.0	10	10				
KINSEKI LTD.	HC-49/U (-S)	8.0	10	10	0* ¹	(i)		
		12.0	5	5				
		16.0	OPEN	OPEN				
	P3	32.768kHz	30	33	120k	(iii)		

* Models with an asterisk have the built-in ground capacitance (C₁, C₂).

*¹ The series resistor for XTAL can reduce the effect of the noise caused by the electrostatic discharge.

Mask Option Table

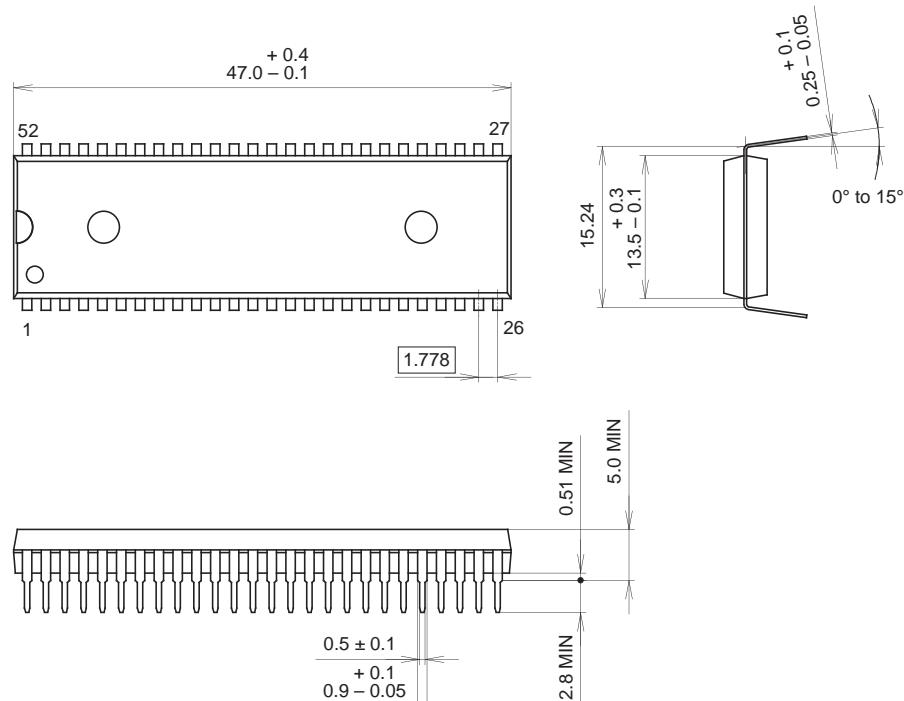
Item	Content	
Reset pin pull-up resistor	Non-existent	Existant

Fig. 13. Characteristic curves

Package Outline

Unit: mm

52PIN SDIP (PLASTIC)

**PACKAGE STRUCTURE**

SONY CODE	SDIP-52P-01
EIAJ CODE	SDIP052-P-0600
JEDEC CODE	-----

PACKAGE MATERIAL	EPOXY RESIN
LEAD TREATMENT	SOLDER/PALLADIUM PLATING
LEAD MATERIAL	COPPER ALLOY
PACKAGE MASS	5.6g

NOTE : PALLADIUM PLATING

This product uses S-PdPPF (Sony Spec.-Palladium Pre-Plated Lead Frame).